

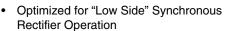


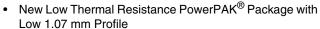
N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)		
30	0.0040 at V _{GS} = 10 V	25	47		
	0.0048 at V _{GS} = 4.5 V	23	4/		

FEATURES

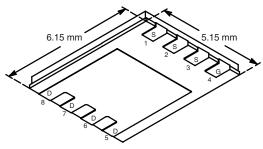
- · Halogen-free available
- TrenchFET[®] Power MOSFET





• 100 % R_g Tested





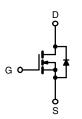
Bottom View

Ordering Information: Si7886ADP-T1-E3 (Lead (Pb)-free)

Si7886ADP-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- DC/DC Converters
- · Synchronous Rectifiers



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise n	oted		
Parameter	Symbol	10 s	Steady State	Unit	
Drain-Source Voltage		V_{DS}	30		V
Gate-Source Voltage		V_{GS}	± 12		
Continuous Drain Current (T _{.I} = 150 °C) ^a	T _A = 25 °C	- I _D	25	15	
Continuous Diain Current (1) = 150 C)	T _A = 70 °C		20	12	
Pulsed Drain Current (10 μs Pulse Width)		I _{DM}	60		Α
Continuous Source Current (Diode Conduction) ^a		I _S	4.5	1.6	
Avalanche Current	L = 0.1 mH	I _{AS}	50		
Single Pulse Avalanche Energy	L = 0.1 IIII1	E _{AS}	125		mJ
Mariana Darray Dissinational	T _A = 25 °C		5.4	1.9	W
Maximum Power Dissipation ^a	T _A = 70 °C		3.4	1.2	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C
Soldering Recommendations (Peak Temperature) ^{b, c}			260		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	t ≤ 10 s	R _{thJA}	18	23	°C/W
Maximum Junction-to-Ambient	Steady State		50	65	
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	1.0	1.5	

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

Vishay Siliconix



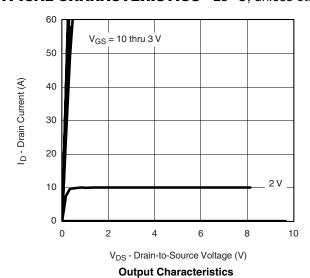
SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Condition Min.		Тур.	Max.	Unit	
Static							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.6	1	1.5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zana Oala Valla va Busin Oamani	1	V _{DS} = 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			5	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
	В	$V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}$		0.0032	0.0040	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 23 \text{ A}$		0.0037	0.0048		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 25 A	V _{DS} = 15 V, I _D = 25 A			S	
Diode Forward Voltage ^a	V_{SD}	$I_S = 2.9 \text{ A}, V_{GS} = 0 \text{ V}$		0.7	1.1	V	
Dynamic ^b	•		•	•			
Input Capacitance	C _{iss}			6450		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{SS} = 0 \text{ V}, f = 1 \text{ kHz}$		873			
Reverse Transfer Capacitance	C _{rss}			402			
Total Gate Charge	Q_g			47	60		
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 25 \text{ A}$		12.5		nC	
Gate-Drain Charge	Q_{gd}			9.0			
Gate Resistance	R_g		0.5	1.0	1.5	Ω	
Turn-On Delay Time	t _{d(on)}			17	30		
Rise Time	t _r	V_{DD} = 15 V, R_L = 15 Ω		14	25	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 1.0 A, V_{GEN} = 10 V, R_G = 6 Ω		158	230		
Fall Time	t _f			43	65		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 2.9 A, di/dt = 100 A/μs		50	80		

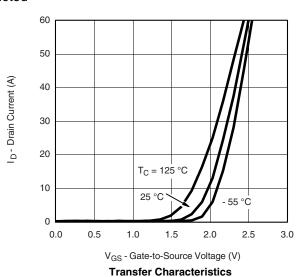
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



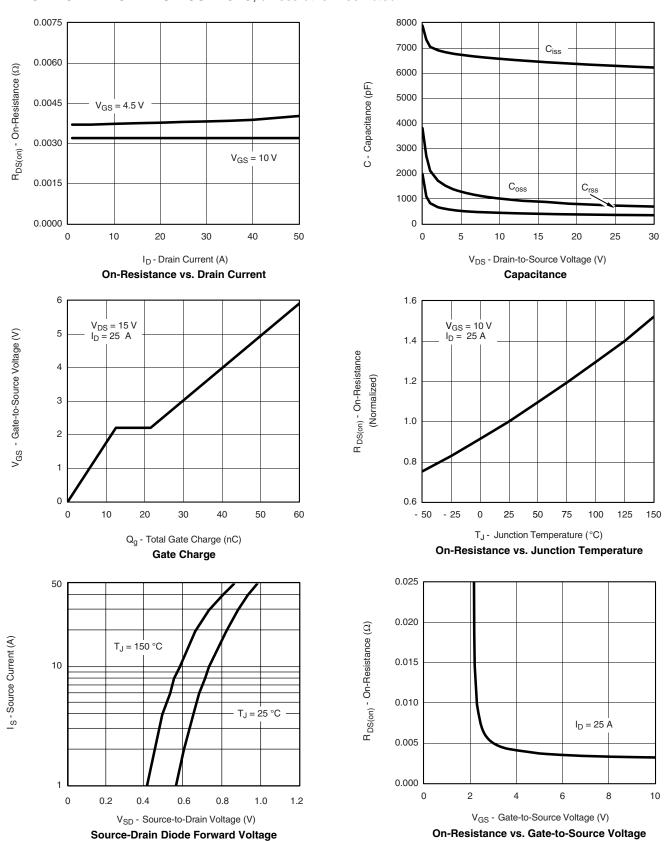








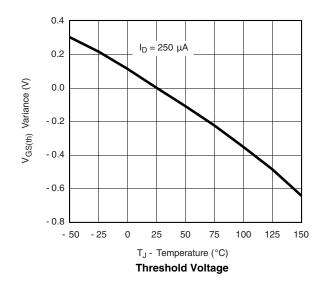
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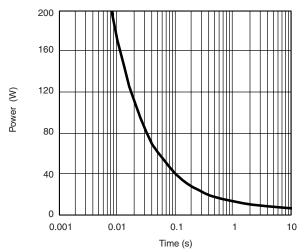


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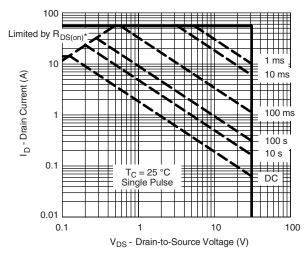
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



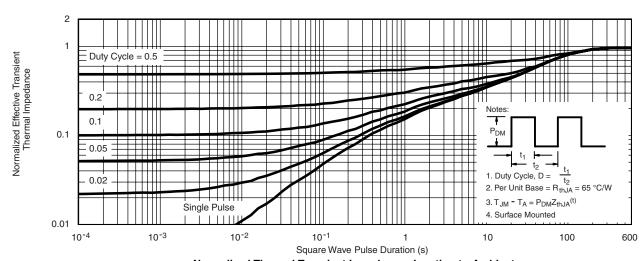


Single Pulse Power, Junction-to-Ambient



 * V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

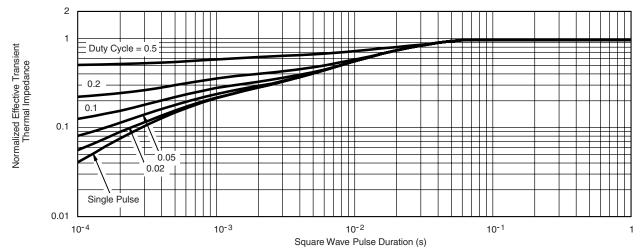
Safe Operating Area, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?73156.

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